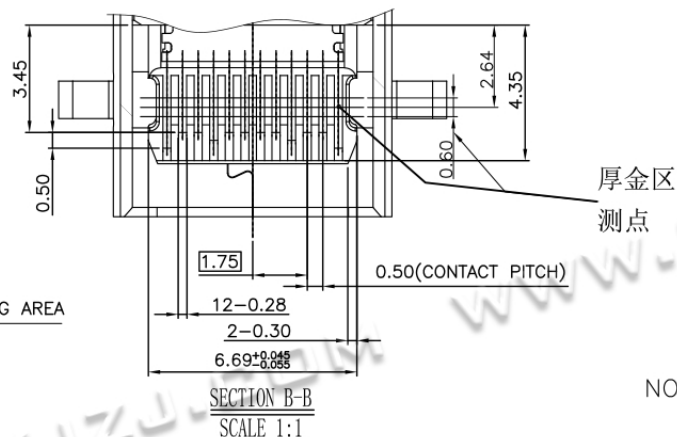
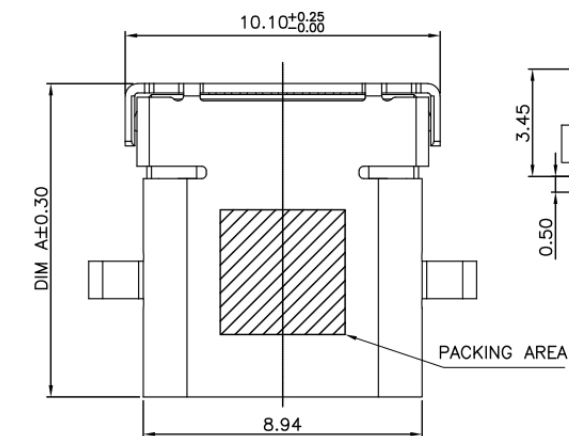
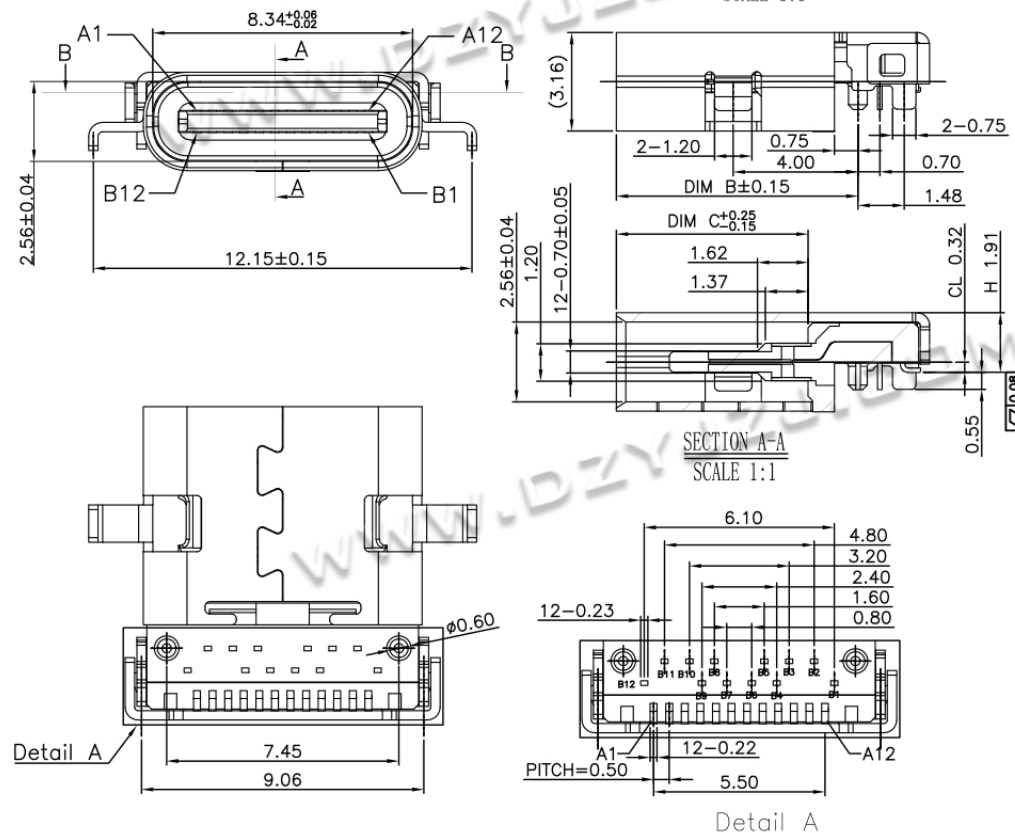




NO	DIM A	DIM B	DIM C
1	10.0	7.75	6.2
2	8.65	6.4	4.85

- NOTES:
- MATERIAL:
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
PLATED GOLD ON CONTACT AREA,
G/F GOLD ON SOLDER AREA,
50u" NICKEL PLATING OVER ALL.
SHELL: SUS304-H,T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
SHILD: SUS304-H,T=0.12±0.03mm
 - MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N.
DURABILITY: 10000 CYCLES
 - ELECTRICAL:
CURRENT: 5A MAX FOR VBUS;
1.25A FOR GND, 0.25A FOR OTHER OTHER.
VOLTAGE: 20VDC MAX
WITHSTANDING VOLTAGE: 100V AC.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.
 - ENVIRONMENTAL
TEMPERATURE RANGE: -30°C TO +80°C

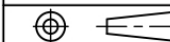


深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X.* ±2° X.X* ±0.5°



UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

CHECKED BY :

马跃

DATE :

2014-02-23

APPROVED BY :

邱敏

DATE :

2014-02-23

PART NAME:

USB TYPE C 母座沉板DIP+SMT

PART NO.

HYC125-USBC24-XXX

MOLD NO.

DRAW NO:

HYC-2211142301

SHEET NO.

1 OF 1

